RLT Series Low-Resistance Thick Film Chip Resistors Product Specification

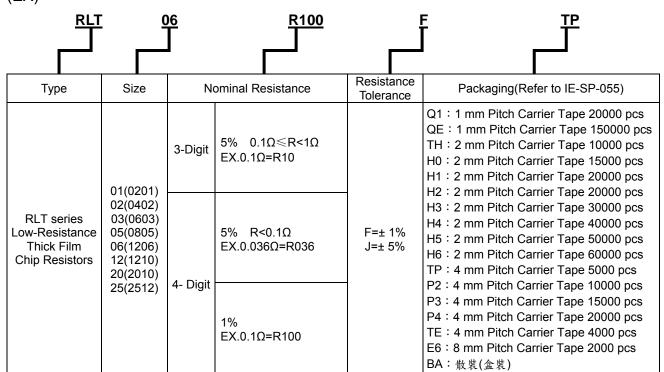
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1 Scope:

- 1.1 This specification is applicable to lead free and halogen free of RoHS directive for RLT series Low-Resistance thick film chip resistors.
- 1.2 The product is for general electronic purpose.

2 Explanation Of Part Numbers:

(EX)



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3 General Specifications

	Rated	Max. Rated	Max. Overload	T.C.R	Resistance Range
Туре	Power at 70°C	Current	Current	(ppm / °C)	F(±1%) \ J((±5%) E-24 \ E-96
DI TOA	4			±900	$100~m\Omega \leqq R < 200~m\Omega$
RLT01 (0201)	$\frac{1}{20}$ W	0.70A	1.76A	±800	$200 \text{ m}\Omega \leq R < 500\text{m}\Omega$
, ,				±700	$500 \text{ m}\Omega \leq \text{R} < 1000 \text{ m}\Omega$
5.1 5.2 5.2 1.2	4			±1600	$20~\text{m}\Omega \leqq \text{R} < 100~\text{m}\Omega$
RLT02 (0402)	1/16W	1.77A	4.42A	±800	100 mΩ \leq R < 500mΩ
, ,				±700	$500 \text{ m}\Omega \leq R < 1000 \text{ m}\Omega$
5.1 5.2 5.2 1.2	4			±1500	$10 \text{ m}\Omega \leq R < 100 \text{ m}\Omega$
RLT03 (0603)	1/10W	3.16A	7.91A	±800	100 mΩ \leq R < 500mΩ
(2322)	-			±700	$500~\text{m}\Omega \leqq \text{R} < 1000~\text{m}\Omega$
		1/8 W 3.53A 8.82A ±800	±1200	$10~\text{m}\Omega \leqq R < 100~\text{m}\Omega$	
RLT05 (0805)	- <u>1</u> W		±800	$100~\text{m}\Omega \leqq R < 500\text{m}\Omega$	
, ,	-			±600	$500 \text{ m}\Omega \leq R < 1000 \text{ m}\Omega$
5.1 5.2 5.2 1.2	4			±1200	$10 \text{ m}\Omega \leq R < 100 \text{ m}\Omega$
(1206)	RLT06 $\frac{1}{3}$ W 5.77A 14.42A	14.42A	±800	100 mΩ \leq R < 500mΩ	
(3			±600	$500~\text{m}\Omega \leqq \text{R} < 1000~\text{m}\Omega$
				±1200	$10 \text{ m}\Omega \leq R < 100 \text{ m}\Omega$
RLT12 (1210)	$\frac{1}{2}$ W	7.07A	17.67A	±900	100 mΩ \leq R < 500mΩ
(-,				±800	$500 \text{ m}\Omega \leq R < 1000 \text{ m}\Omega$
				±1200	$10 \text{ m}\Omega \leq R < 100 \text{ m}\Omega$
RLT20 (2010)	$\frac{3}{4}$ W	8.66A	21.65A	±1000	$100~\text{m}\Omega \leqq R < 500\text{m}\Omega$
(===,	•			±900	$500~\text{m}\Omega \leqq \text{R} < 1000~\text{m}\Omega$
				±1200	$10~\text{m}\Omega \leqq R < 100~\text{m}\Omega$
RLT25 (2512)	1 W	10A	25A	±1000	$100~\text{m}\Omega \leqq R < 500\text{m}\Omega$
,				±900	$500~\text{m}\Omega \leqq R < 1000~\text{m}\Omega$
	伯	走用溫度範圍		-55°C ~	+155°C (0201: −55°C ~ +125°C)

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3.1 Power Derating Curve:

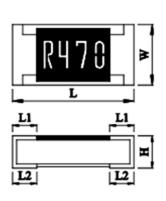
Туре	RLT01 (0201)	Other
Operating Temperature Range	-55°C ~ +125°C	-55°C ~ +155°C
	For resistors operated in ambient temperatures above 70°C, power rating shall be derated in accordance with figure below.	For resistors operated in ambient temperatures above 70°C, power rating shall be derated in accordance with figure below.
Figure	100 80 80 60 0 -55 20 40 60 80 100 120 140 160 Ambient Temperature(°C)	70 80 80 60 0 -55 20 40 60 80 100 120 140 160 Ambient Temperature(°C)

3.2 Current Rating

Rated Current: The resistor shall have a DC continuous working current or a rms. AC continuous working current at commercial-line frequency and wave form corresponding to the power rating, as determined from the following:

$$I=\sqrt{P/R}$$
 I= Rated current (A) P= Power rating (w) R= Nominal resistance(Ω)

4 Dimensions:



						Unit:mm
Туре	Dimension Size Code	L	W	Н	L1	L2
RLT01	0201	0.60±0.03	0.30±0.03	0.23±0.03	0.15±0.05	0.15±0.05
RLT02	0402	1.00±0.10	0.50±0.05	0.30±0.10	0.25±0.10	0.20±0.15
RLT03	0603	1.60±0.10	0.80±0.10	0.45±0.10	0.25±0.15	0.35±0.15
RLT05	0805	2.00±0.10	1.25±0.10	0.50±0.10	0.35±0.20	0.35±0.20
RLT06	1206	3.05±0.10	1.55±0.10	0.50±0.10	0.45±0.20	0.35±0.15
RLT12	1210	3.05±0.10	2.55±0.10	0.55±0.10	0.50±0.20	0.50±0.20
RLT20	2010	5.00±0.20	2.50±0.20	0.60±0.10	0.65±0.20	0.65±0.20
RLT25	2512	6.30±0.20	3.20±0.20	0.60±0.10	0.65±0.20	0.65±0.20

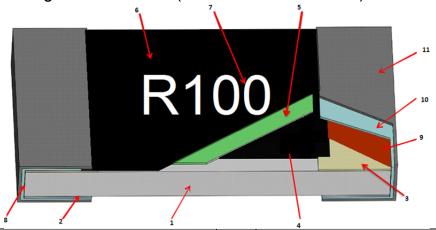
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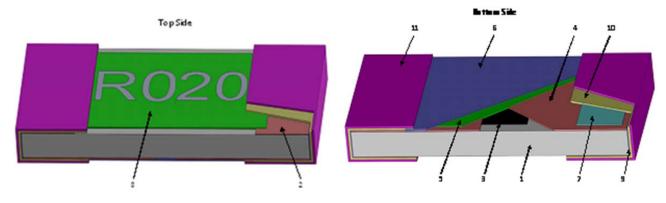
5 Structure Graph:

5.1 Resistance Range : $R \ge 100 \text{ m}\Omega$ (Not include 0201/0402)



1	Ceramic substrate	7	Marking
2	Bottom inner electrode	8	Terminal inner electrode
3	Top inner electrode	9	Cu plating
4	Resistive layer	10	Ni plating
5	1st Protective coating	11	Sn plating
6	2nd Protective coating		

5.2 Resistance Range : (0603~2512 R < 100m Ω)&(0201/0402 all resistance)



1	Ceramic substrate	7	2nd Bottom inner electrode
2	Top inner electrode	8	G2 layer+Marking
3	Resistive layer	9	Terminal inner electrode
4	Bottom inner electrode	11	Ni plating
5	1st Protective coating	12	Sn plating
6	2nd Protective coating		

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6 Reliability Test:

6.1 Electrical Performance Test

Item	Conditions	Specifications
пеш	Conditions	Resistors
Temperature Coefficient of Resistance	TCR (ppm / °C) = $\frac{(R2-R1)}{R1 (T2-T1)}$ ×10 ⁶ R1: Resistance at room temperature R2: Resistance at -55°C or +125°C T1: Room temperature T2: Temperature -55°C or +125°C	Refer to item 3. general specifications
Short Time Overload	Applied 2.5 times rated current for 5 seconds and release the load for about 30 minutes, then measure its resistance variance rate. (Rated current refer to item 3. general specifications) Refer to JIS-C5201-1 4.13	ΔR=±2.0%
Insulation Resistance	Put the resistor in the fixture, add 100 VDC in + ,- terminal for 60 sec then measured the insulation resistance between electrodes and insulating enclosure or between electrodes and base material. Refer to JIS-C5201-1 4.6 Metal block measuring plote Metal plote measuring point B Specimen Pressurizing by spring No.5mm	$\geq 10^9 \Omega$
Dielectric Withstand Voltage	Put the resistor in the fixture, add VAC (see SPEC below) in +,-terminal for. RLT05、06、12、20、25 apply 500 VAC 1 minute. RLT01、02、03 apply 300 VAC 1 minute. Refer to JIS-C5201-1 4.7	No short or burned on the appearance.
Intermittent Overload	Put the tested resistor in chamber under temperature 25±2°C and load 2.5 times rated DC current for 1 sec on, 25 sec off, ${}^{10000}_{}^{+400}_{0}$ test cycles, then it be left at no-load for 1 hour , then measure its resistance variance rate. Refer to JIS-C5201-1 4.13	ΔR=±5.0%

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6.2 Mechanical Performance Test

Item	Conditions	Specifications Resistors
Terminal Strength	Test 1: The resistor mounted on the board applied 5N pushing force on the sample rear for 10 sec. Test 2: The resistor mounted on the board slowlyadd force on the sample rear until the sampletermination is breakdown. Refer to JIS-C5201-1 4.16	
Resistance to Solvent	The tested resistor be immersed into isopropyl alcohol of 20~25℃ for 5 minutes, then the resistor is left in the room for 48 hrs, and measured its resistance variance rate. Refer to JIS-C5201-1 4.29	ΔR=±2.0%
Solderability	Preconditioning Put the tested resistor in the apparatus of PCT, at a temperature of 105°C, humidity of 100% RH, and pressure of 1.22×105 Pa for a duration of 4 hours. Then after left the tested resistor in room temperature for 2 hours or more. Test method: The resistor be immersed into solder pot in temperature 235±5°C for 2 sec, then the resistor is left as placed under microscope to observed its solder area. Refer to JIS-C5201-1 4.17	Solder coverage over 95%
Resistance to Soldering Heat	for 10 seconds. Then the resistor is left in the room for 1 hour. ©Test method 2 (Solder pot test): The tested resistor be immersed into molten solder of 260+5/-0°C for 30 seconds. Then the resistor is left as placed under microscope to observe its solder area.	Test item 1: ΔR%=±2.0% Test item 2: (1).Solder coverage over 95%. (2).The underlying material (such as ceramic) shall not be visible at the crest corner area of the electrode. Test item 3: ΔR%=±2.0%

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Item	Conditions	Specifications Resistors
Joint Strength of Solder		Resistors ΔR%=±2.0%
	Refer to JIS-C5201-1 4.33	

6.3 Environmental Test

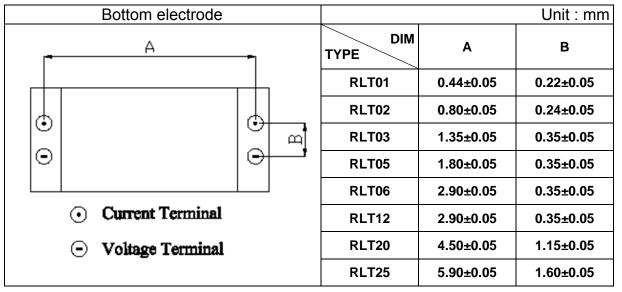
Item	Conditions		Specifications	
пеш			Resistors	
Resistance to Dry Heat	Put tested resistor in chamber under temperature 155±5°C for 1000 +48/-0 hours. Then leaving the tested resistor in room temperature for 60 minutes, and measure its resistance variance rate. Refer to JIS-C5201-1 4.25		∆R=±2.0%	
Thermal Shock	Put the tested resistor in the chamber to which shown in the following table shal consecutively. Then leaving the tested temperature for 1 hours, and measure Testing Condi Lowest Temperature Highest Temperature Temperature-retaining time Refer to MIL-STD 202 Method 107	I be repeated 300 times resistor in the room its resistance variance rate.	ΔR=±2.0%	
Loading Life in Moisture	Put the tested resistor in the chamber under temperature 40±2°C, relative humidity 90~95% and load the rated current for 90 minutes on, 30 minutes off, total 1000 hours. Then leaving the tested resistor in room temperature for 60 minutes, and measure its resistance variance rate. Refer to JIS-C5201-1 4.24		∆R=±3.0%	
Load Life	Put the tested resistor in chamber under temperature 70±2°C and load the rated current for 90 minutes on, 30 minutes off, total 1000 hours. Then leaving the tested resistor in room temperature for 60 minutes, and measure its resistance variance rate. Refer to JIS-C5201-1 4.25		∆R=±3.0%	

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7 Measurement Point:



8 Plating Thickness:

8.1 Ni: \ge 2 μ m

8.2 Sn(Tin): \ge 3 μ m

8.3 Cu: \ge **2** μ m

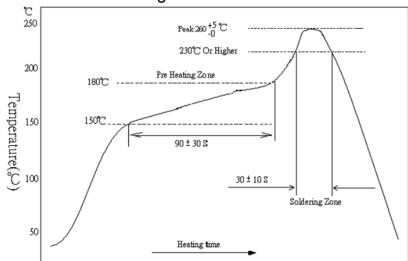
8.4 Sn(Tin):Matte Sn

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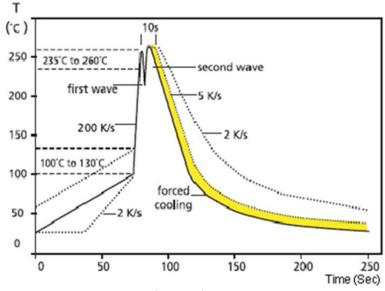
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- 9 Technical application notes: (This is for recommendation, please customer perform adjustment according to actual application)
 - 9.1 Recommend Soldering Method:
 - 9.1.1 Lead Free IR Reflow Soldering Profile



Remark: The peak temperature of soldering heat is 260 +5/-0 °C for 10 seconds

9.1.2 Lead Free Double-Wave Soldering Profile.



9.1.3 Soldering Iron: temperature $350^{\circ}\text{C} \pm 10^{\circ}\text{C}$, dwell time shall be less than 3 sec.

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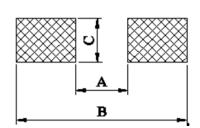
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Unit:mm

9.2 Recommend Land Pattern Design (For Reflow Soldering)

When a component is soldered, the resistance after soldering changes slightly depending on the size of the soldering area and the amount of soldering. When designing a circuit, it is necessary to consider the effect of a decrease or increase in its resistance.



		_	O m
DIM TYPE	Α	В	С
RLT01	0.3	1.0	0.4
RLT02	0.5	1.5	0.6
RLT03	0.8	2.1	0.9
RLT05	1.2	3.0	1.3
RLT06	2.2	4.2	1.6
RLT12	2.2	4.2	2.8
RLT20	3.5	6.1	2.8
RLT25	3.8	8.0	3.5

9.3 Environment Precautions:

This specification product is for general electronic use, RALEC will not be responsible for any damage, cost or loss caused by using this specification product in any special environment. If other applications need to confirm with RALEC.

If consumer intends to use our Company product in special environment or condition (including but not limited to those mentioned below), then will need to make individual recognition of product features and reliability accordingly.

- (a) Used in high temperature and humidity environment;
- (b) Exposed to sea breeze or other corrosive gas, such as Cl2 \ H2S \ NH3 \ SO2 and NO2;
- (c) Used in non-verified liquids including water, oil, chemical and organic solvents;
- (d) Using non-verified resin or other coating material to seal or coat our Company product;
- (e) After soldering, it is necessary to use water-soluble detergents to clean residual solder
- (f) fluxes, even though no-clean fluxes are recommended.

9.4 Momentary Overload Precautions:

The product might be out of function when momentary overloaded. Please make sure to avoid momentary overloading while using and preserving.

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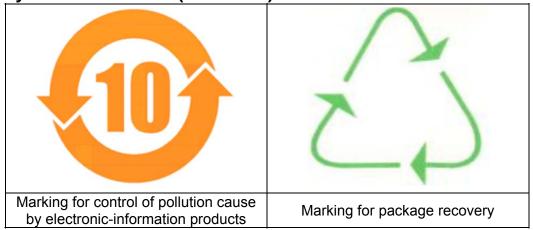
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- 9.5 Operation and Processing Precautions:
 - (a) Avoid damage to the edge of resistor and protective layer caused by mechanical stress.
 - (b) Handle with care when printing circuit board (PCB) is divided or fixed on support body, because bending of printing circuit board (PCB) mounting will make mechanical stress for resistors.
 - (c) Make sure the power rating is under the limit when using the resistor. When power rating is over the limit, the resister will be overloaded. There might be machinery damage due to the climbing temperature.
 - (d) If the resister will be exposed under massive impact load (shock wave) in a short period of time, the working environment must be set up well before use.
 - (e) Please make evaluation and confirmation when the product is well used in your company and have a through consideration of it's fail-safe design to ensure the system safety.

10 Stock period:

- 10.1 The temperature condition must be controlled at 25±5℃, the R.H. must be controlled at 60±15%. The stock can maintain quality level in two years.
- 10.2 Please avoid the mentioned harsh environment below when storing to ensure product performance and its' weldability. Places exposed to sea breeze or other corrosive gas, such as Cl₂ \ H₂S \ NH₃ \ SO₂ and NO₂.
- 10.3 When the product is moved and stored, please ensure the correct orientation of the box. Do not drop or squeeze the box. Otherwise, the electrode or the body of the product may be damaged.

11 The carton packaged for electronic-information products is made by the symbol as follows: (For china)



12 Attachments:

12.1 Document Revise Record (QA-QR-027)

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